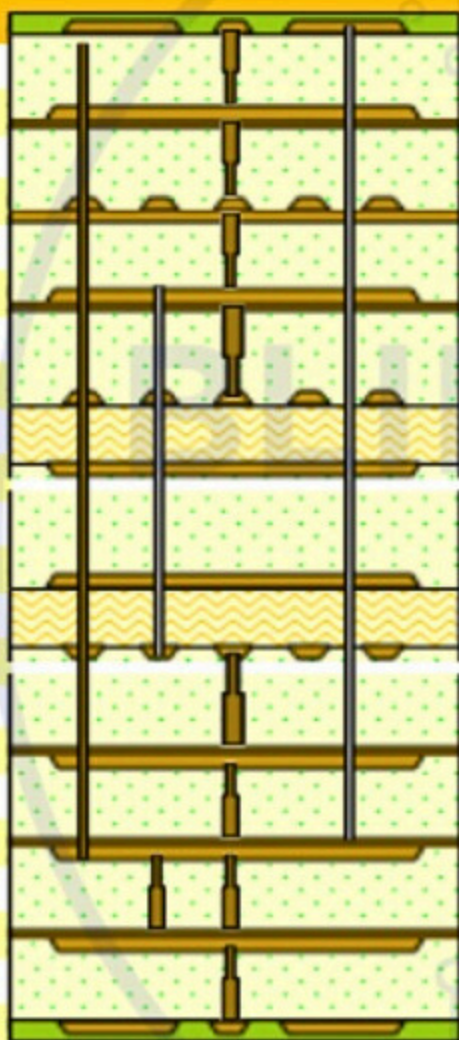


## Rigid PCB Stackup

Layer	Cu Thick. (mils)	Cu Foil wt (oz)	DK	Lam. Thick. (mils)	Description
1	1.55	.375 oz			Foil .375 oz
2	0.65	.375 oz	3.41	2.61	Prepreg I-Speed 1067(74) 18.25Gx24.25 Foil .375 oz
3	0.65	.375 oz	3.56	3.24	Prepreg I-Speed 1086(66.5) 18.25Gx24.25 Foil .375 oz
4	0.60	.5 oz	3.49	3.83	Prepreg I-Speed 1086(70) 18.25Gx24.25 Foil .5 oz
5	0.60	0.5 oz	3.42	3.75	Prepreg I-Speed 1078(73.5) 18.25Gx24.25
6	0.60	0.5 oz	3.77	4.00	Core I-Speed 4.00mils 3313 0.5 oz / 0.5 oz VLP2 18.25Gx24.25
7	0.60	0.5 oz	3.51	3.10	Prepreg I-Speed 1080(69) 18Gx24
8	0.60	0.5 oz	3.77	4.00	Core I-Speed 4.00mils 3313 0.5 oz / 0.5 oz VLP2 18.25Gx24.25
9	0.60	.5 oz	3.42	3.75	Prepreg I-Speed 1078(73.5) 18.25Gx24.25 Foil .5 oz
10	0.65	.375 oz	3.49	3.83	Prepreg I-Speed 1086(70) 18.25Gx24.25 Foil .375 oz
11	0.65	.375 oz	3.56	3.41	Prepreg I-Speed 1086(66.5) 18.25Gx24.25 Foil .375 oz
12	1.55	.375 oz	3.41	2.61	Prepreg I-Speed 1067(74) 18.25Gx24.25 Foil .375 oz



### Special Stackup Requirements:

A: Buried Vias 4-9, Micro Vias 4-5, Micro Vias 9-8

B: Micro Vias 3-4, Micro Vias 10-9

C: Micro Vias 2-3, Micro Vias 11-10

D: Through holes 1-12, NCVF (FLAT) 1-12, Micro Vias 1-2, Micro Vias 12-11

44.33 Thickness over Laminate  
47.43 Thickness over Copper  
48.43 Thickness over Soldermask